150 mA CMOS Low Dropout Regulator

The NCP103 is 150 mA LDO that provides the engineer with a very stable, accurate voltage with low noise suitable for space constrained, noise sensitive applications. In order to optimize performance for battery operated portable applications, the NCP103 employs the dynamic quiescent current adjustment for very low I_Q consumption at no–load.

Features

- Operating Input Voltage Range: 1.7 V to 5.5 V
- Available in Fixed Voltage Options: 0.9 V to 3.5 V Contact Factory for Other Voltage Options
- Very Low Quiescent Current of Typ. 50 µA
- Standby Current Consumption: Typ. 0.1 µA
- Low Dropout: 75 mV Typical at 150 mA
- ±1% Accuracy at Room Temperature
- High Power Supply Ripple Rejection: 75 dB at 1 kHz
- Thermal Shutdown and Current Limit Protections
- Stable with a 1 µF Ceramic Output Capacitor
- Available in uDFN 1.0 x 1.0 mm Package
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applicaitons

- PDAs, Mobile phones, GPS, Smartphones
- Wireless Handsets, Wireless LAN, Bluetooth[®], Zigbee[®]
- Portable Medical Equipment
- Other Battery Powered Applications



Figure 1. Typical Application Schematic



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XX = Specific Device Code M = Date Code

PIN CONNECTION



ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 14 of this data sheet.



*Active output discharge function is present only in NCP103AMXyyyTCG devices. yyy denotes the particular V_{OUT} option.

Figure 2. Simplified Schematic Block Diagram

PIN FUNCTION DESCRIPTION

Pin No.	Pin Name	Description
1	OUT	Regulated output voltage pin. A small ceramic capacitor with minimum value of 1 μ F is needed from this pin to ground to assure stability.
2	GND	Power supply ground.
3	EN	Driving EN over 0.9 V turns on the regulator. Driving EN below 0.4 V puts the regulator into shutdown mode.
4	IN	Input pin. A small capacitor is needed from this pin to ground to assure stability.
-	EPAD	Exposed pad should be connected directly to the GND pin. Soldered to a large ground copper plane allows for effective heat removal.

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Input Voltage (Note 1)	V _{IN}	–0.3 V to 6 V	V
Output Voltage	Vout	–0.3 V to VIN + 0.3 V or 6 V	V
Enable Input	Ven	–0.3 V to VIN + 0.3 V or 6 V	V
Output Short Circuit Duration	tsc	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	s
Maximum Junction Temperature	T _{J(MAX)}	150	°C
Storage Temperature	T _{STG}	-55 to 150	°C
ESD Capability, Human Body Model (Note 2)	ESD _{HBM}	2000	V
ESD Capability, Machine Model (Note 2)	ESD _{MM}	200	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Refer to ELECTRICAL CHĂRACTERISTIS and APPLICATION INFORMATION for Safe Operating Area.

2. This device series incorporates ESD protection and is tested by the following methods:

ESD Human Body Model tested per EIA/JESD22-A114,

ESD Machine Model tested per EIA/JESD22-A115,

Latchup Current Maximum Rating tested per JEDEC standard: JESD78.

THERMAL CHARACTERISTICS (Note 3)

Rating		Value	Unit
Thermal Characteristics, uDFN4 1x1 mm Thermal Resistance, Junction–to–Air	$R_{ hetaJA}$	170	°C/W

3. Single component mounted on 1 oz, FR 4 PCB with 645 mm² Cu area.

ELECTRICAL CHARACTERISTICS $-40^{\circ}C \le T_J \le 85^{\circ}C$; $V_{IN} = V_{OUT(NOM)} + 1 V$ for V_{OUT} options greater than 1.5 V. Otherwise $V_{IN} = 2.5 V$, whichever is greater; $I_{OUT} = 1 \text{ mA}$, $C_{IN} = C_{OUT} = 1 \mu$ F, unless otherwise noted. $V_{EN} = 0.9 V$. Typical values are at $T_J = +25^{\circ}C$. Min./Max. are for $T_J = -40^{\circ}C$ and $T_J = +85^{\circ}C$ respectively.

Parameter	Test Condition	Test Conditions			Тур	Max	Unit
Operating Input Voltage			V _{IN}	1.7		5.5	V
	4000 17 10500	$V_{OUT} \le 2.0 \text{ V}$	V _{OUT}	-40		+40	mV
Output Voltage Accuracy	$-40^{\circ}C \le T_J \le 85^{\circ}C$	V _{OUT} > 2.0 V		-2		+2	%
Line Regulation	$Vout + 0.5 \ V \leq Vin \leq 5.5$	V (V _{IN} ≥ 1.7 V)	Reg _{LINE}		0.01	0.1	%/V
Load Regulation	IOUT = 1 mA to 1	50 mA	Reg _{LOAD}		10	30	mV
Load Transient	I _{OUT} = 1 mA to 150 mA or in 1 μs, C _{OUT} =		Tran _{LOAD}		-30/ +20		mV
		V _{OUT} = 1.5 V			180	235	mV
		V _{OUT} = 1.85 V			120	165	
	450	V _{OUT} = 2.8 V	V _{DO}		75	125	
Dropout Voltage (Note 4)	l _{OUT} = 150 mA	V _{OUT} = 3.0 V			72	120	
		V _{OUT} = 3.1 V			70	120	
		V _{OUT} = 3.3 V			65	110	
Output Current Limit	V _{OUT} = 90% V _{OU}	V _{OUT} = 90% V _{OUT(nom)}		150	550		mA
Ground Current	Iout = 0 mA	IOUT = 0 mA			50	95	μΑ
Shutdown Current	$Ven \le 0.4 \text{ V}, \text{ Vin} = 5.5 \text{ V}$		I _{DIS}		0.01	1	μΑ
EN Pin Threshold Voltage High Threshold Low Threshold	V _{EN} Voltage incr V _{EN} Voltage deci	V _{EN} Voltage increasing V _{EN} Voltage decreasing		0.9		0.4	V
EN Pin Input Current	VEN = 5.5	Ven = 5.5 V			0.3	1.0	μΑ
Power Supply Rejection Ratio	V _{IN} = 3.6 V, V _{OUT} = 3.1 V I _{OUT} = 150 mA	f = 1 kHz	PSRR		75		dB
Output Noise Voltage	V _{IN} = 2.5 V, V _{OUT} = 1.8 V, f = 10 Hz to 100	$V_{IN} = 2.5 \text{ V}, V_{OUT} = 1.8 \text{ V}, I_{OUT} = 150 \text{ mA}$ f = 10 Hz to 100 kHz			60		μV_{rms}
Thermal Shutdown Temperature	Temperature increasing f	Temperature increasing from $T_J = +25^{\circ}C$			160		°C
Thermal Shutdown Hysteresis	Temperature falling	Temperature falling from T _{SD}			20		°C
Active Output Discharge Resistance	ve Output Discharge Resistance VEN < 0.4 V, Version A only		R _{DIS}		100		Ω

4. Characterized when Vout falls 100 mV below the regulated voltage at VIN = VOUT(NOM) + 1 V.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.









	RMS Output Noise (µV)			
lout	10 Hz – 100 kHz	100 Hz – 100 kHz		
1 mA	60.93	59.11		
10 mA	52.73	50.63		
150 mA	51.20	48.96		





	RMS Output Noise (μV)				
IOUT	10 Hz – 100 kHz	100 Hz – 100 kHz			
1 mA	79.23	74.66			
10 mA	75.03	70.37			
150 mA	77.28	72.66			

Figure 21. Output Voltage Noise Spectral Density for V_{OUT} = 2.8 V, C_{OUT} = 1 μ F



	RMS Output Noise (μV)			
IOUT	10 Hz – 100 kHz	100 Hz – 100 kHz		
1 mA	80.17	75.29		
10 mA	81.28	76.46		
150 mA	81.31	76.77		













4 μs/div

Figure 34. Load Transient Response – Rising Edge, V_{OUT} = 1.2 V, I_{OUT} = 1 mA to 150 mA, C_{OUT} = 1 μ F, 4.7 μ F



 $\begin{array}{l} 4 \ \mu \text{s/div} \\ \text{Figure 36. Load Transient Response - Rising} \\ \text{Edge, V}_{\text{OUT}} = 2.8 \ \text{V, I}_{\text{OUT}} = 1 \ \text{mA to 150 mA,} \\ \\ C_{\text{OUT}} = 1 \ \mu \text{F, 4.7 } \mu \text{F} \end{array}$



Figure 33. Line Transient Response – Falling Edge, V_{OUT} = 2.8 V, I_{OUT} = 150 mA



Figure 35. Load Transient Response – Falling Edge, V_{OUT} = 1.2 V, I_{OUT} = 1 mA to 150 mA,



Figure 37. Load Transient Response – Falling Edge, V_{OUT} = 2.8 V, I_{OUT} = 1 mA to 150 mA, C_{OUT} = 1 μF, 4.7 μF



2 μs/div









Figure 39. Load Transient Response – Falling Edge, V_{OUT} = 2.8 V, I_{OUT} = 1 mA to 150 mA, V_{IN} = 3.8 V, 5.5 V



Figure 41. Short–Circuit and Thermal Shutdown

APPLICATIONS INFORMATION

General

The NCP103 is a high performance 150 mA Low Dropout Linear Regulator. This device delivers very high PSRR (over 75 dB at 1 kHz) and excellent dynamic performance as load/line transients. In connection with very low quiescent current this device is very suitable for various battery powered applications such as tablets, cellular phones, wireless and many others. The device is fully protected in case of output overload, output short circuit condition and overheating, assuring a very robust design.

Input Capacitor Selection (CIN)

It is recommended to connect at least a 1μ F Ceramic X5R or X7R capacitor as close as possible to the IN pin of the device. This capacitor will provide a low impedance path for unwanted AC signals or noise modulated onto constant input voltage. There is no requirement for the min. /max. ESR of the input capacitor but it is recommended to use ceramic capacitors for their low ESR and ESL. A good input capacitor will limit the influence of input trace inductance and source resistance during sudden load current changes. Larger input capacitor may be necessary if fast and large load transients are encountered in the application.

Output Decoupling (C_{OUT})

The NCP103 requires an output capacitor connected as close as possible to the output pin of the regulator. The recommended capacitor value is 1 μ F and X7R or X5R dielectric due to its low capacitance variations over the specified temperature range. The NCP103 is designed to remain stable with minimum effective capacitance of 0.22 μ F to account for changes with temperature, DC bias and package size. Especially for small package size capacitors such as 0402 the effective capacitance drops rapidly with the applied DC bias.

There is no requirement for the minimum value of Equivalent Series Resistance (ESR) for the C_{OUT} but the maximum value of ESR should be less than 3 Ω . Larger output capacitors and lower ESR could improve the load transient response or high frequency PSRR. It is not recommended to use tantalum capacitors on the output due to their large ESR. The equivalent series resistance of tantalum capacitors is also strongly dependent on the temperature, increasing at low temperature.

Enable Operation

The NCP103 uses the EN pin to enable/disable its device and to deactivate/activate the active discharge function.

If the EN pin voltage is <0.4 V the device is guaranteed to be disabled. The pass transistor is turned–off so that there is virtually no current flow between the IN and OUT. The active discharge transistor is active so that the output voltage V_{OUT} is pulled to GND through a 100 Ω resistor. In the disable state the device consumes as low as typ. 10 nA from the $V_{\rm IN}$.

If the EN pin voltage >0.9 V the device is guaranteed to be enabled. The NCP103 regulates the output voltage and the active discharge transistor is turned–off.

The EN pin has internal pull-down current source with typ. value of 300 nA which assures that the device is turned-off when the EN pin is not connected. In the case where the EN function isn't required the EN should be tied directly to IN.

Output Current Limit

Output Current is internally limited within the IC to a typical 550 mA. The NCP103 will source this amount of current measured with a voltage drops on the 90% of the nominal V_{OUT} . If the Output Voltage is directly shorted to ground ($V_{OUT} = 0$ V), the short circuit protection will limit the output current to 580 mA (typ). The current limit and short circuit protection will work properly over whole temperature range and also input voltage range. There is no limitation for the short circuit duration.

Thermal Shutdown

When the die temperature exceeds the Thermal Shutdown threshold ($T_{SD} - 160^{\circ}$ C typical), Thermal Shutdown event is detected and the device is disabled. The IC will remain in this state until the die temperature decreases below the Thermal Shutdown Reset threshold ($T_{SDU} - 140^{\circ}$ C typical). Once the IC temperature falls below the 140°C the LDO is enabled again. The thermal shutdown feature provides the protection from a catastrophic device failure due to accidental overheating. This protection is not intended to be used as a substitute for proper heat sinking.

Power Dissipation

As power dissipated in the NCP103 increases, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and the ambient temperature affect the rate of junction temperature rise for the part.

The maximum power dissipation the NCP103 can handle is given by:

$$P_{D(MAX)} = \frac{\left[125^{\circ}C - T_{A}\right]}{\theta_{JA}}$$
 (eq. 1)

The power dissipated by the NCP103 for given application conditions can be calculated from the following equations:

$$\mathsf{P}_\mathsf{D} \approx \mathsf{V}_\mathsf{IN} \big(\mathsf{I}_\mathsf{GND} @ \mathsf{I}_\mathsf{OUT} \big) + \mathsf{I}_\mathsf{OUT} \big(\mathsf{V}_\mathsf{IN} - \mathsf{V}_\mathsf{OUT} \big) \qquad (\text{eq. 2})$$



Figure 42. 0JA vs. Copper Area (uDFN4)

Reverse Current

The PMOS pass transistor has an inherent body diode which will be forward biased in the case that $V_{OUT} > V_{IN}$. Due to this fact in cases, where the extended reverse current condition can be anticipated the device may require additional external protection.

Power Supply Rejection Ratio

The NCP103 features very good Power Supply Rejection ratio. If desired the PSRR at higher frequencies in the range 100 kHz - 10 MHz can be tuned by the selection of C_{OUT} capacitor and proper PCB layout.

Turn-On Time

The turn–on time is defined as the time period from EN assertion to the point in which V_{OUT} will reach 98% of its

nominal value. This time is dependent on various application conditions such as $V_{OUT(NOM)}$, C_{OUT} and T_A . For example typical value for $V_{OUT} = 1.2$ V, $C_{OUT} = 1 \mu F$, $I_{OUT} = 1$ mA and $T_A = 25^{\circ}C$ is 90 μ s.

PCB Layout Recommendations

To obtain good transient performance and good regulation characteristics place C_{IN} and C_{OUT} capacitors close to the device pins and make the PCB traces wide. In order to minimize the solution size, use 0402 capacitors. Larger copper area connected to the pins will also improve the device thermal resistance. The actual power dissipation can be calculated from the equation above (Equation 2). Expose pad should be tied the shortest path to the GND pin.

ORDERING INFORMATION

Device	Voltage Option	Marking	Marking Rotation	Option	Package	Shipping [†]
NCP103AMX090TCG	0.9 V	AQ	0°			
NCP103AMX100TCG	1.0 V	5	180°			
NCP103AMX105TCG	1.05 V	А	0°			
NCP103AMX110TCG	1.1 V	E	180°			
NCP103AMX120TCG	1.2 V	D	0°			
NCP103AMX125TCG	1.25 V	D	180°			
NCP103AMX130TCG	1.3 V	AD	0°			
NCP103AMX150TCG	1.5 V	E	0°			
NCP103AMX160TCG	1.6 V	Y	180°			
NCP103AMX180TCG	1.8 V	К	180°			
NCP103AMX185TCG	1.85 V	F	0°			
NCP103AMX210TCG	2.1 V	Р	180°			
NCP103AMX220TCG	2.2 V	R	180°	With active output	uDFN4	
NCP103AMX240TCG	2.4 V	AL	0°	discharge function	(Pb-Free)	3000 / Tape & Reel
NCP103AMX250TCG	2.5 V	AX	0°			
NCP103AMX260TCG	2.6 V	V	180°			
NCP103AMX270TCG	2.7 V	AK	0°			
NCP103AMX280TCG	2.8 V	J	0°			
NCP103AMX285TCG	2.85 V	К	0°			
NCP103AMX300TCG	3.0 V	L	0°			
NCP103AMX310TCG	3.1 V	Р	0°			
NCP103AMX320TCG	3.2 V	AY	0°			
NCP103AMX330TCG	3.3 V	Q	0°			
NCP103AMX345TCG	3.45 V	AE	0°			
NCP103AMX350TCG	3.5 V	3	180°			
NCP103AMX360TCG	3.6 V	AV	0°			
NCP103BMX100TCG	1.0 V	5	270°			
NCP103BMX105TCG	1.05 V	А	90°			
NCP103BMX110TCG	1.1 V	E	270°			
NCP103BMX120TCG	1.2 V	D	90°			
NCP103BMX125TCG	1.25 V	D	270°			
NCP103BMX130TCG	1.3 V	CD	0°			
NCP103BMX150TCG	1.5 V	E	90°			
NCP103BMX160TCG	1.6 V	Y	270°			
NCP103BMX180TCG	1.8 V	К	270°			
NCP103BMX185TBG	1.85 V	CJ	0°			
NCP103BMX185TCG	1.85 V	CJ	0°	Without active output	uDFN4	
NCP103BMX210TCG	2.1 V	Р	270°	discharge function		3000 / Tape & Reel
NCP103BMX220TCG	2.2 V	R	270°			
NCP103BMX250TCG	2.5 V	СН	0°			
NCP103BMX260TCG	2.6 V	V	270°			
NCP103BMX280TCG	2.8 V	J	90°			
NCP103BMX285TCG	2.85 V	K	90°			
NCP103BMX300TCG	3.0 V	L	90°			
NCP103BMX310TCG	3.1 V	P	90°			
NCP103BMX330TCG	3.3 V	Q	90°			
NCP103BMX345TCG	3.45 V	CE	0°			
						-

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



NOTES: 1. DIMENSIONING AND TOLERANCING PER

- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.03 AND 0.07
- FROM THE TERMINAL TIPS.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

THE THE THE THE				
	MILLIMETERS			
DIM	MIN	MAX		
Α		0.60		
A1	0.00	0.05		
A3	0.15 REF			
b	0.20	0.30		
D	1.00 BSC			
D2	0.38	0.58		
Е	1.00 BSC			
е	0.65 BSC			
L	0.20	0.30		
L2	0.27	0.37		

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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